

Datasheet revision 1.0

www.Proto-Advantage.com

Compact Series Adapter Top Side IC Stencil and Secondary Reflow Spacer

Description

Custom thickness assembly spacer to hold compact adapter bottom pins so that the top side IC footprint can be stenciled using our stainless-steel solder paste stencils. Also holds the bottom side pins in place for secondary reflow after top side IC is placed onto stenciled solder paste.

Designed to handle multiple lead-free (260°C) reflow cycles.

Reusable. Suitable for 100+ reflow cycles.

NOTES:

- 1) Plug compact adapter pins into the smaller holes. The larger holes are there to allow sufficient airflow during reflow to ensure even PCB heating.
- 2) Fits Compact adapters up to DIP-60. For larger compact adapters, two or more of these COMP-TOP-STENCIL-HELP-1 spacers can be used side by side to hold bottom pins in place during secondary reflow.



Image 1: Spacer ships in a panel. Separate at mouse bites.

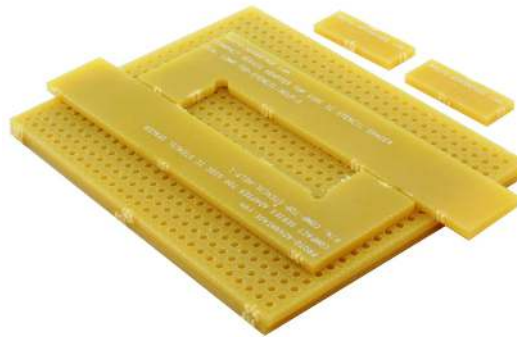


Image 2: Spacer mouse bites removed, to allow stack to be built to accept compact adapter.



Image 3: Spacer stack with compact adapter in place, ready for stencil to be taped down on top.